

BEST AVAILABLE COPY**AMENDMENTS TO THE CLAIMS**

Claim 1 (Currently amended): A method of forming at least one wire on a substrate, the substrate comprising
5 at least one conductive region, an insulating layer disposed on the substrate, and the insulating layer comprising at least one recess exposing the conductive region, the method comprising:

forming a barrier layer on a surface of the insulating
10 layer and the recess;

forming a continuous and uniform conductive layer on a surface of the barrier layer, the conductive layer comprising an aluminum layer or a tungsten layer;

forming a seed layer on a surface of the conductive
15 layer and interlaying the conductive layer between the seed layer and the barrier layer; and

forming a metal layer on a surface of the seed layer, and the metal layer filling up the recess.

20 Claim 2 (Original): The method of claim 1 wherein the substrate comprises a semiconductor wafer or a silicon-on-insulator substrate (SOI substrate).

Claim 3 (Original): The method of claim 1 wherein the
25 conductive region comprises a source of a transistor, a gate of a transistor, a drain of a transistor, a lower level wire, a landing pad, or a resistor.

Claim 4 (Original): The method of claim 1 wherein the
30 recess is a via hole of a dual damascene structure.

Claim 5 (Original): The method of claim 1 wherein the

barrier layer comprises a silicon nitride layer, a titanium nitride layer (TiN layer), a tantalum nitride layer (TaN layer), or a tantalum nitride/tantalum (TaN/Ta) composite metal layer.

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Claim 6 (Canceled)

Claim 7 (Original): The method of claim 1 wherein a thickness of the conductive layer ranges from 5 to 400 angstroms (Å).

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Claim 8 (Original): The method of claim 1 wherein the method for forming the conductive layer comprises a chemical vapor deposition (CVD) process or an atomic layer deposition (ALD) process.

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Claim 9 (Original): The method of claim 1 wherein the seed layer is a copper layer formed by a physical vapor deposition (PVD) process.

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Claim 10 (Original): The method of claim 1 wherein the seed layer is a copper alloy layer formed by a physical vapor deposition (PVD) process.

Claim 11 (Original): The method of claim 1 wherein a thickness of the seed layer ranges from 5 to 2000 angstroms (Å).

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Claim 12 (Original): The method of claim 1 wherein the metal layer is formed by an electric copper plating (ECP) process.

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Claim 13 (Currently amended): A method of forming at least one dual damascene wire on a substrate, the substrate comprising at least one conductive region, an insulating layer disposed on the substrate, and the
5 insulating layer comprising at least one trench pattern and via hole pattern stacked from top to bottom exposing the conductive region, the method comprising:

forming a barrier layer on a surface of the insulating layer, the trench pattern, and the via hole pattern;
10 forming a continuous and uniform conductive layer on a surface of the barrier layer, the conductive layer comprising an aluminum layer or a tungsten layer;

forming a seed layer on a surface of the conductive layer and interlaying the conductive layer between the
15 seed layer and the barrier layer; and

forming a metal layer on a surface of the seed layer, and the metal layer filling up the trench pattern and the via hole pattern.

20 Claim 14 (Currently amended): The method of claim 13 wherein the substrate ~~comprise~~ comprises a semiconductor wafer or a silicon-on-insulator substrate (SOI substrate).

25 Claim 15 (Original): The method of claim 13 wherein the conductive region comprises a source of a transistor, a gate of a transistor, a drain of a transistor, a lower level wire, a landing pad, or a resistor.

30 Claim 16 (Original): The method of claim 13 wherein the barrier layer comprises a silicon nitride layer, a titanium nitride layer (TiN layer), a tantalum nitride

layer (TaN layer), or a tantalum nitride/tantalum (TaN/Ta) composite metal layer.

Claim 17 (Canceled)

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Claim 18 (Original): The method of claim 13 wherein the method for forming the conductive layer comprises a chemical vapor deposition (CVD) process or an atomic layer deposition (ALD) process, and a thickness of the
10 conductive layer ranges from 5 to 400 angstroms (Å).

Claim 19 (Original): The method of claim 13 wherein the seed layer is a copper layer formed by a physical vapor deposition (PVD) process, and a thickness of the
15 seed layer ranges from 5 to 2000 angstroms (Å).

Claim 20 (Original): The method of claim 13 wherein the seed layer is a copper alloy layer formed by a physical vapor deposition (PVD) process, and a
20 thickness of the seed layer ranges from 5 to 2000 angstroms (Å).

Claim 21 (Original): The method of claim 13 wherein the metal layer is formed by an electric copper plating
25 (ECP) process.

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